

Description

OhmegaPly PT RCM is a Nickel Phosphorus thin film metal alloy electro-deposited on an enhanced nodule copper foil for improved adhesion.

OhmegaPly PT RCM Product Matrix

COPPER TYPE	SHEET RESISTIVITY (OHMS PER SQUARE)						
PT GRADE	10	25	40	50	100	250	377-FS
½ oz (18 µm)	0.5R10PT/ 0.5A10PT	0.5A25PT	0.5A40PT	0.5A50PT	0.5A100PT	0.5A250PT	0.5A377PT
1 oz (35 µm)	1A10PT	1A25PT		1A50PT	1A100PT	1A250PT	

Table 1: Ohmega material offerings on PT enhanced nodule based copper

Representative Base Copper Foil Data

Grade	Thickness (µm)	Area Weight (g/m ²)	Rz (µm)	Tensile Strength (kg/mm ²)	Elongation (%)	Peel Strength (kg/cm)
PT	18	167	6.4	42	8.0	1.0 ⁽¹⁾
	35	335	7.6	39	15.0	1.5 ⁽¹⁾

Table 2: Representative Data. (1) Base copper foil peel strength on FR4 substrate

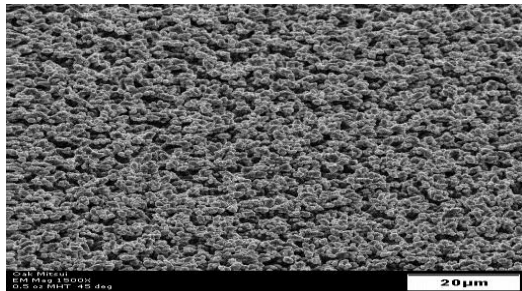


Figure 1: PT base copper foil matte side

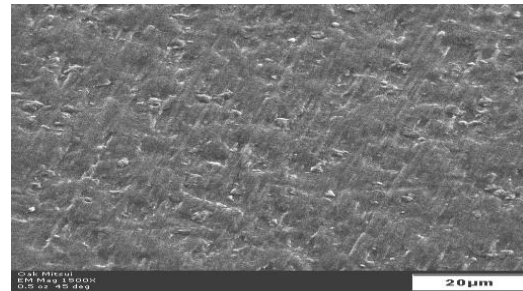


Figure 2: PT base copper foil drum side

OhmegaPly® PT RCM Technical Snap-Shot

Sheet Resistivities	10	25	40	50	100	250	377-FS	Unit	Remark and Condition
Material Tolerance	+/-5	+/-5	+/-5	+/-5	+/-5	+/-10	+/-10	%	Sheet Resistivity
Power Load Test	172	99	91	84	69	59	53	mW	Based on 0.50mm x 0.25mm resistor size on FR4, no cladding.
RTC	20	50	75	75	100	100	400	PPM/°C	MIL-STD-202-304, -55°C to 125°C
Solder Float	0.2	0.5	0.8	0.8	1.0	0.5	0.7	Δ R%	MIL-STD-202-210D, 288°C, 10 sec, 3x

Table 3: OhmegaPly PT RCM representative data, not a guarantee

* OhmegaPly RCM® and or OhmegaPly® Laminate is exported from the United States in accordance with the Export Administration regulations. Diversion contrary to United States law prohibited